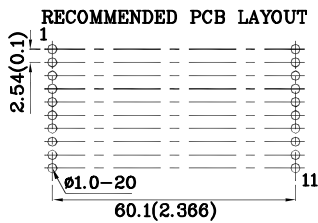
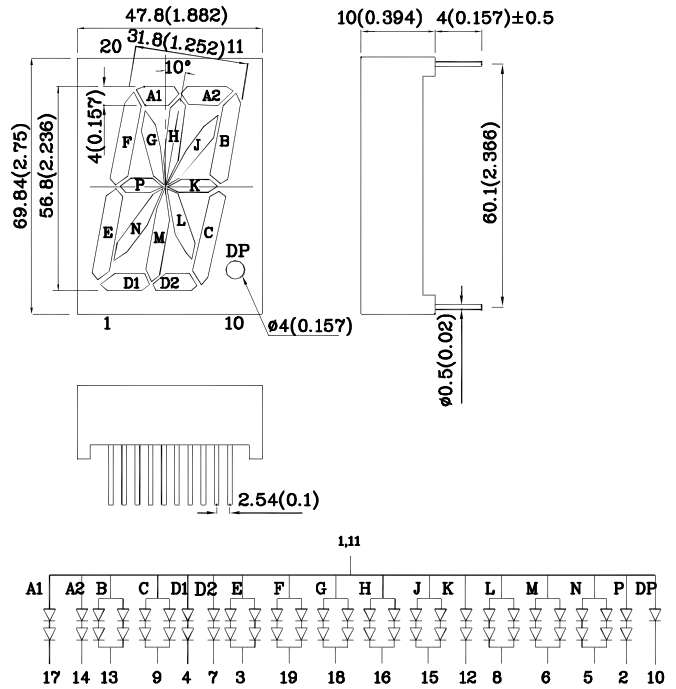


Features

- Low power consumption
- Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant



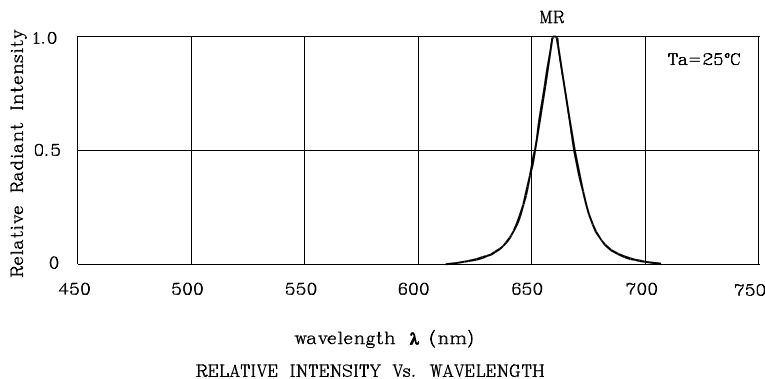
Package Schematics



Notes:

1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01") unless otherwise noted.
2. Specifications are subject to change without notice.

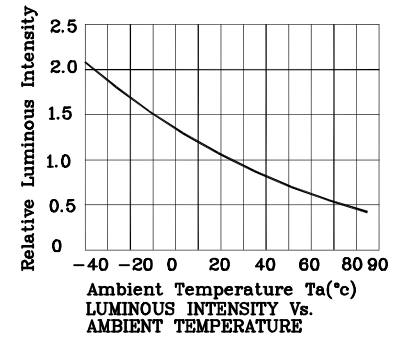
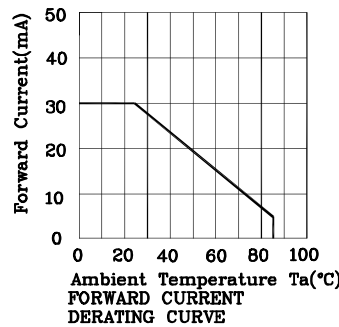
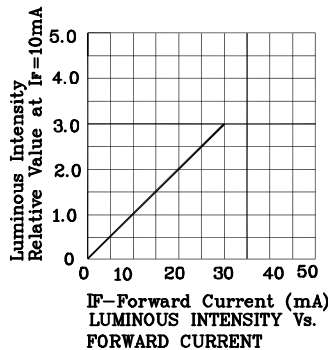
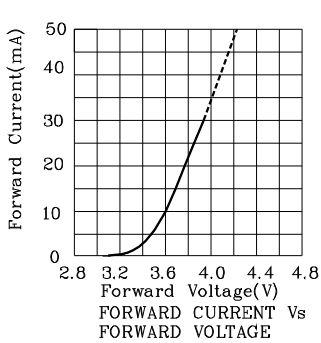
| Part Number | Emitting Color | Emitting Material | Luminous Intensity (I _F =10mA) ucd | | Wavelength nm λP | Description |
|-------------|----------------|-------------------|--|-------|------------------------|---------------------------------|
| | | | min. | typ. | | |
| XAMR60A | Red | GaAlAs | 21000 | 43990 | 660 | Common Anode, Rt. Hand Decimal. |



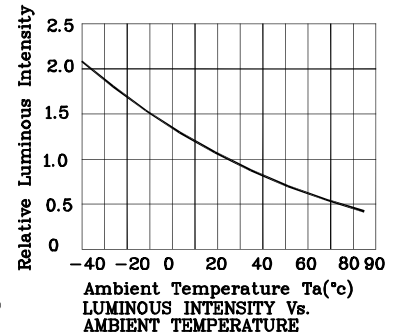
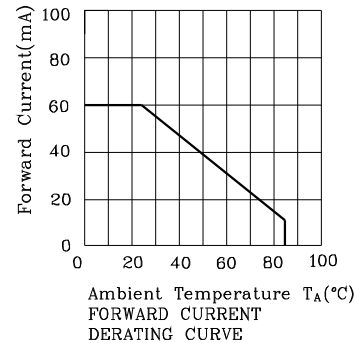
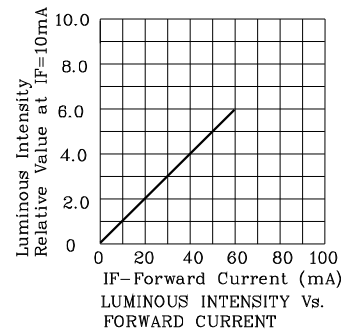
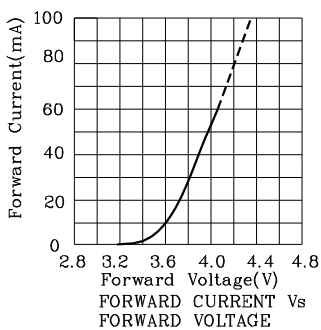
| Absolute maximum ratings (TA=25°C) | | | UR (GaAsP/GaP) | Unit |
|--|-------------------------|-----------|-------------------|------|
| Reverse Voltage | A1,A2,D1, D2,P,K | VR | 5 | V |
| | B,C,E,F,G, H,J,L,M,N | | 5 | |
| | DP | | 5 | |
| Forward Current | A1,A2,D1, D2,P,K | IF | 30 | mA |
| | B,C,E,F,G, H,J,L,M,N | | 60 | |
| | DP | | 30 | |
| Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width | A1,A2,D1, D2,P,K | iFS | 155 | mA |
| | B,C,E,F,G, H,J,L,M,N | | 310 | |
| | DP | | 155 | |
| Power Dissipation | A1,A2,D1, D2,P,K | PD | 150 | mW |
| | B,C,E,F,G, H,J,L,M,N | | 300 | |
| | DP | | 75 | |
| Operating Temperature | TA | -40 ~ +85 | °C | |
| Storage Temperature | Tstg | -40 ~ +85 | | |
| Lead Solder Temperature [2mm Below Package Base] | 260°C For 3~5 Seconds | | | |

| Operating Characteristics (TA=25°C) | | | UR (GaAsP/GaP) | Unit |
|---|-------------------------|-----|-------------------|------|
| Forward Voltage (Typ.) (IF=10mA) | A1,A2,D1,D2, P,K | VF | 3.6 | V |
| | B,C,E,F,G,H, J,L,M,N | | 1.8 | |
| | DP | | 1.8 | |
| Forward Voltage (Max.) (IF=10mA) | A1,A2,D1,D2, P,K | VF | 5.0 | V |
| | B,C,E,F,G,H, J,L,M,N | | 2.5 | |
| | DP | | 2.5 | |
| Reverse Current (Max.) (VR=5V) | A1,A2,D1,D2, P,K | IR | 10 | uA |
| Reverse Current (Max.) (VR=5V) | B,C,E,F,G,H, J,L,M,N | | 20 | |
| Reverse Current (Max.) (VR=5V) | DP | | 10 | |
| Wavelength of Peak Emission (Typ.) (IF=10mA) | λP | 660 | nm | |
| Wavelength of Dominant Emission (Typ.) (IF=10mA) | λD | 640 | nm | |
| Spectral Line Full Width At Half- Maximum (Typ.) (IF=10mA) | Δλ | 20 | nm | |
| Capacitance (Typ.) (VF=0V, f=1MHz) | C | 45 | pF | |

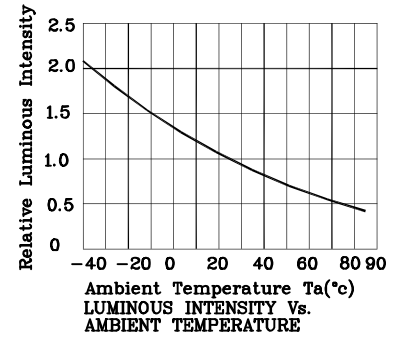
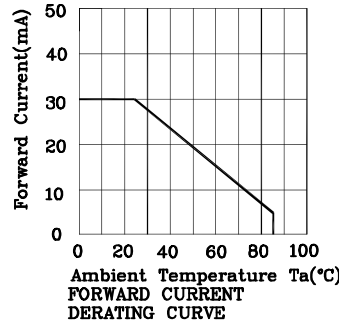
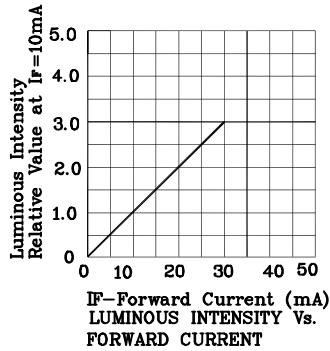
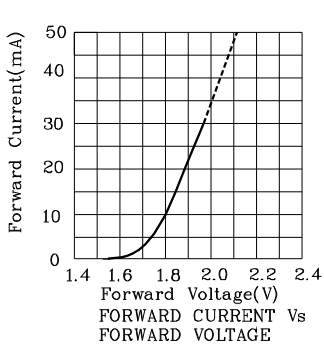
❖ MR



Note:the curves are on the segment a1,a2,d1,d2,p,k.

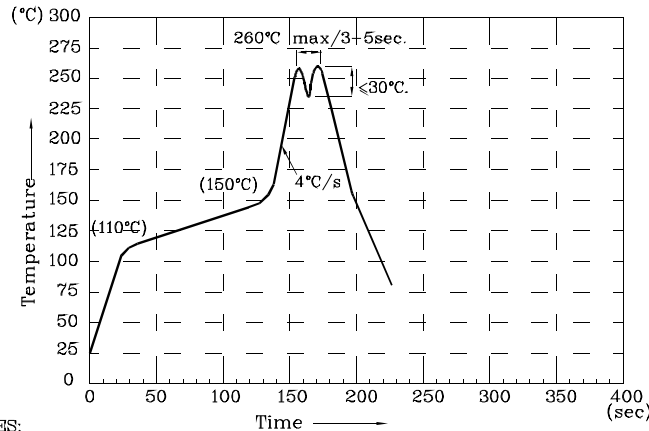


Note:the curves are on the segment b,c,e,f,g,h,j,l,m,n.



Note: the curves are on the DP.

Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering, the PCB top-surface temperature should be kept below 105°C.
5. No more than once.

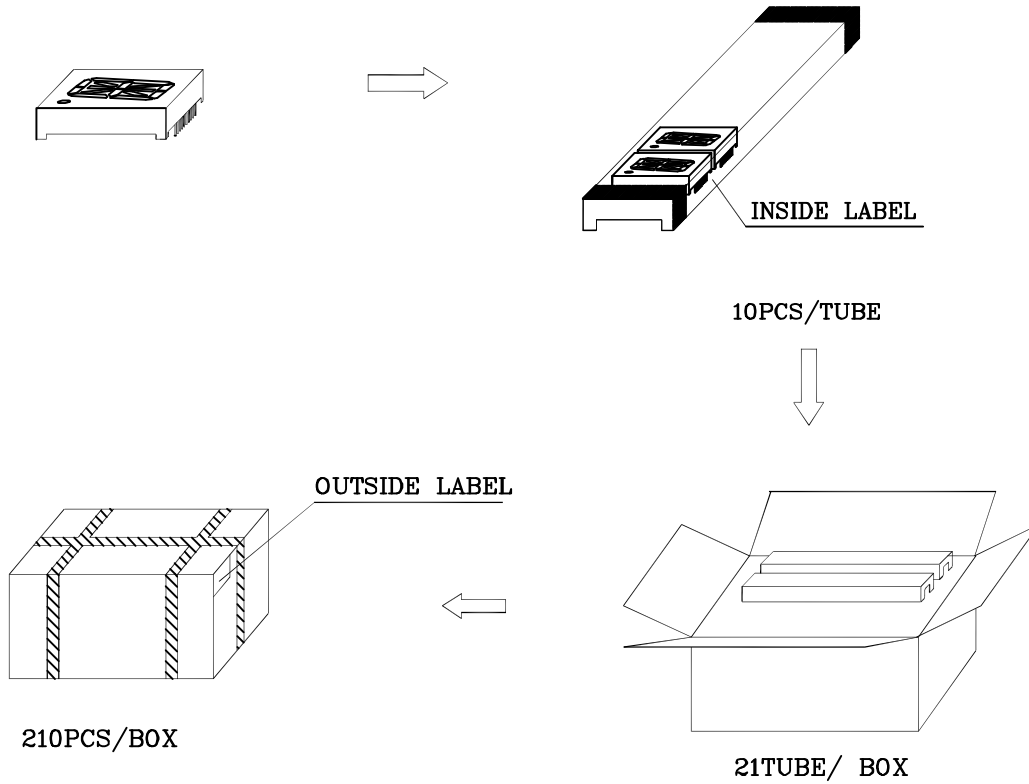
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

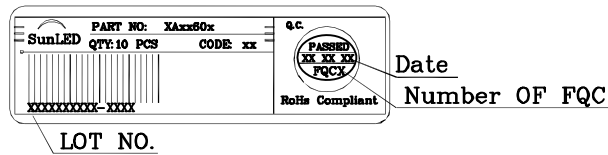
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box

